

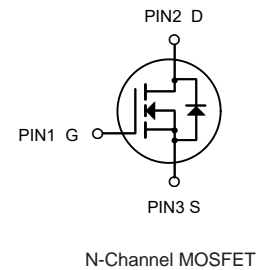


## Description

The NDS351N uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.



**SOT-23**



## General Features

$V_{DS} = 30V$   $I_D = 4A$

$R_{DS(ON)} < 38m\Omega @ V_{GS}=10V$

## Application

Battery protection

Load switch

Uninterruptible power supply

## Package Marking and Ordering Information

| Product ID | Pack   | Brand      | Qty(PCS) |
|------------|--------|------------|----------|
| NDS351N    | SOT-23 | HXY MOSFET | 3000     |

## Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

| Symbol          | Parameter   | Limit      | Unit         |
|-----------------|---|------------|--------------|
| $V_{DS}$        | Drain-Source Voltage  | 30         | V            |
| $V_{GS}$        | Gate-Source Voltage   | $\pm 20$   | V            |
| $I_D$           | Drain Current-Continuous                                    | 4          | A            |
| $I_{DM}$        | Drain Current-Pulsed <sup>(Note 1)</sup>                    | 16.4       | A            |
| $P_D$           | Maximum Power Dissipation                                   | 1          | W            |
| $T_J, T_{STG}$  | Operating Junction and Storage Temperature Range            | -55 To 150 | $^\circ C$   |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup> | 125        | $^\circ C/W$ |



**Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)**

| Symbol        | Parameter   | Test Condition  | Min. | Typ. | Max.      | Units      |
|---------------|---|---|------|------|-----------|------------|
| $V_{(BR)DSS}$ | Drain-Source Breakdown Voltage                            | $V_{GS}=0V, I_D=250\mu A$                                   | 30   | -    | -         | V          |
| $I_{DSS}$     | Zero Gate Voltage Drain Current                           | $V_{DS}=30V, V_{GS}=0V,$                                    | -    | -    | 1.0       | $\mu A$    |
| $I_{GSS}$     | Gate to Body Leakage Current                              | $V_{DS}=0V, V_{GS}=\pm 20V$                                 | -    | -    | $\pm 100$ | nA         |
| $V_{GS(th)}$  | Gate Threshold Voltage                                    | $V_{DS}=V_{GS}, I_D=250\mu A$                               | 1.0  | 1.5  | 2.5       | V          |
| $R_{DS(on)}$  | Static Drain-Source on-Resistance<br><small>note2</small> | $V_{GS}=10V, I_D=4A$  | -    | 29   | 38        | m $\Omega$ |
|               |   | $V_{GS}=4.5V, I_D=3A$                                       | -    | 45   | 65        |            |
| $C_{iss}$     | Input Capacitance   | $V_{DS}=15V, V_{GS}=0V,$<br>$f=1.0MHz$                      | -    | 233  | -         | pF         |
| $C_{oss}$     | Output Capacitance  |   | -    | 44   | -         | pF         |
| $C_{rss}$     | Reverse Transfer Capacitance                              |   | -    | 33   | -         | pF         |
| $Q_g$         | Total Gate Charge   | $V_{DS}=15V, I_D=2A,$<br>$V_{GS}=10V$                       | -    | 3    | -         | nC         |
| $Q_{gs}$      | Gate-Source Charge  |   | -    | 0.5  | -         | nC         |
| $Q_{gd}$      | Gate-Drain("Miller") Charge                               |   | -    | 0.8  | -         | nC         |
| $t_{d(on)}$   | Turn-on Delay Time  | $V_{DS}=15V,$<br>$I_D=4A, R_{GEN}=3\Omega,$<br>$V_{GS}=10V$ | -    | 4    | -         | ns         |
| $t_r$         | Turn-on Rise Time   |   | -    | 2.1  | -         | ns         |
| $t_{d(off)}$  | Turn-off Delay Time                                       |   | -    | 15   | -         | ns         |
| $t_f$         | Turn-off Fall Time  |   | -    | 3.2  | -         | ns         |
| $I_S$         | Maximum Continuous Drain to Source Diode Forward Current  |   | -    | -    | 4         | A          |
| $I_{SM}$      | Maximum Pulsed Drain to Source Diode Forward Current      |   | -    | -    | 16        | A          |
| $V_{SD}$      | Drain to Source Diode Forward Voltage                     | $V_{GS}=0V, I_S=4A$   | -    | -    | 1.2       | V          |

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 0.5\%$

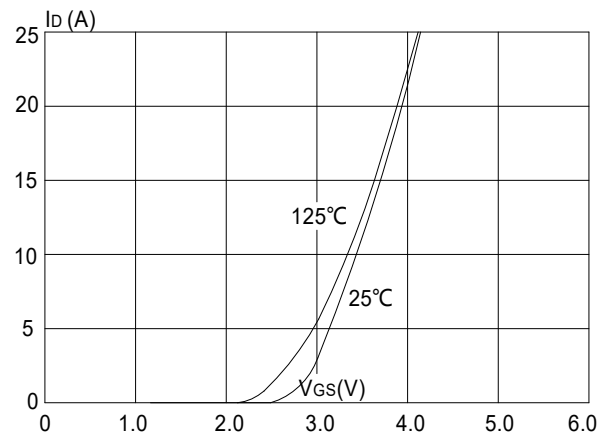


### Typical Characteristics

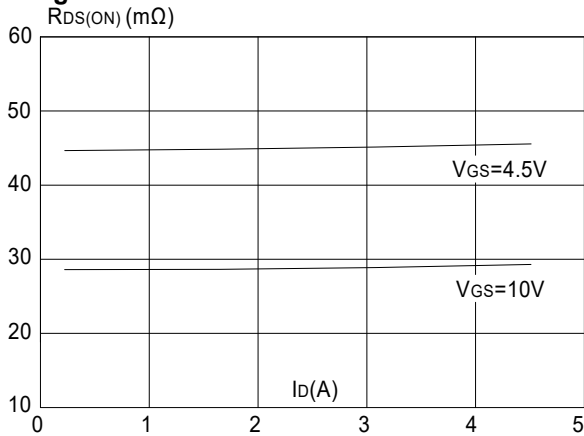
**Figure 1: Output Characteristics**



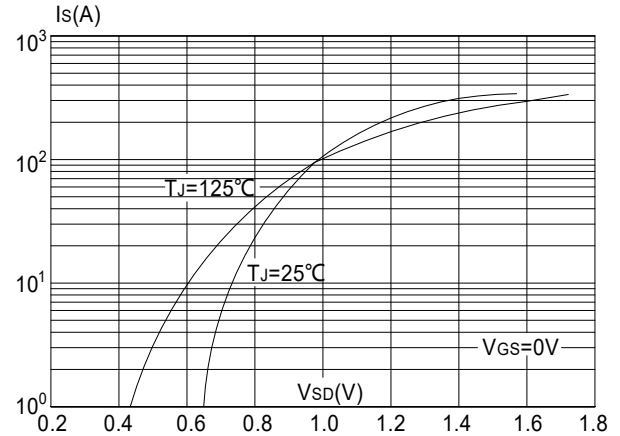
**Figure 2: Typical Transfer Characteristics**



**Figure 3: On-resistance vs. Drain Current**



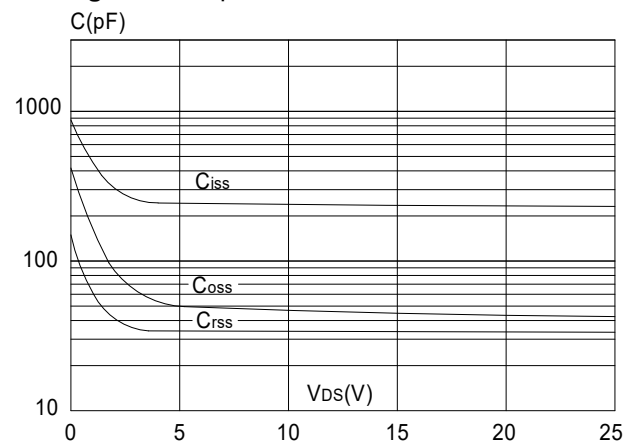
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**



**Figure 6: Capacitance Characteristics**

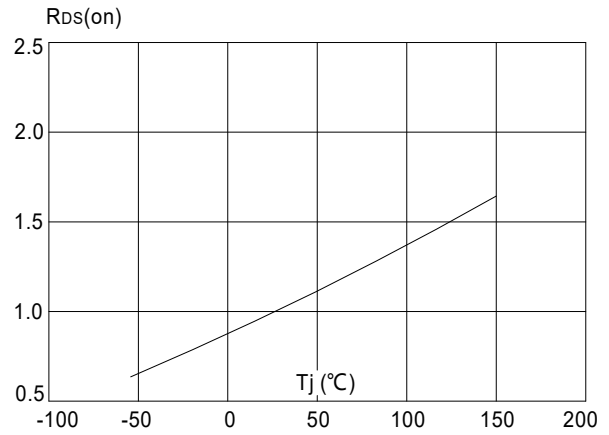




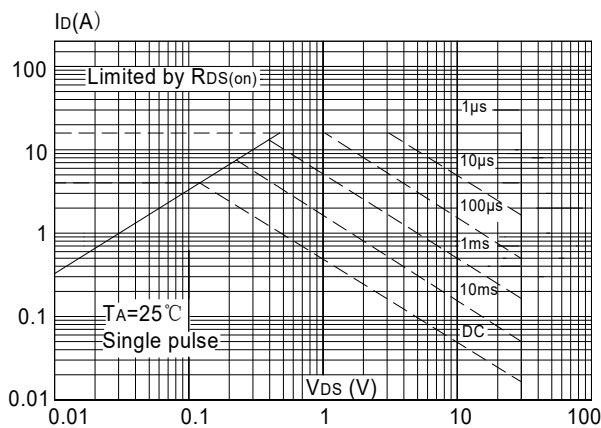
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



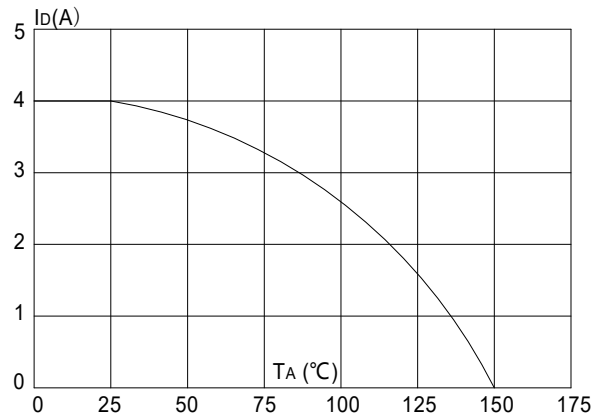
**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



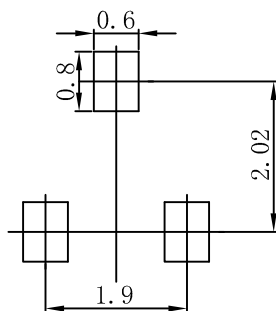


### SOT-23 Package Outline Dimensions



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min                       | Max   | Min                  | Max   |
| A      | 0.900                     | 1.150 | 0.035                | 0.045 |
| A1     | 0.000                     | 0.100 | 0.000                | 0.004 |
| A2     | 0.900                     | 1.050 | 0.035                | 0.041 |
| b      | 0.300                     | 0.500 | 0.012                | 0.020 |
| c      | 0.080                     | 0.150 | 0.003                | 0.006 |
| D      | 2.800                     | 3.000 | 0.110                | 0.118 |
| E      | 1.200                     | 1.400 | 0.047                | 0.055 |
| E1     | 2.250                     | 2.550 | 0.089                | 0.100 |
| e      | 0.950 TYP                 |       | 0.037 TYP            |       |
| e1     | 1.800                     | 2.000 | 0.071                | 0.079 |
| L      | 0.550 REF                 |       | 0.022 REF            |       |
| L1     | 0.300                     | 0.500 | 0.012                | 0.020 |
| θ      | 0°                        | 8°    | 0°                   | 8°    |

### SOT-23 Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05\text{mm}$ .
  3. The pad layout is for reference purposes only.



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